

Abstract

A system for testing semiconductor components contained
5 on a substrate, such as a wafer, a panel, a leadframe or a
module, includes an interconnect configured to electrically
engage all of the components on the substrate at the same
time. The interconnect includes a switching network
configured to selectively apply test signals to selected
10 components, to electrically isolate defective components and
to transmit test signals from selected groups of components.
The system also includes a test apparatus, such as a wafer
prober or a carrier for handling the substrate. A method for
testing includes the steps of providing the interconnect
15 having the switching network, and controlling test signals to
the components using the switching network to perform various
test procedures, such as functionality tests, parametric
tests and burn-in tests.

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